SamHop Microelectronics Corp.

## SDP/B55N03L

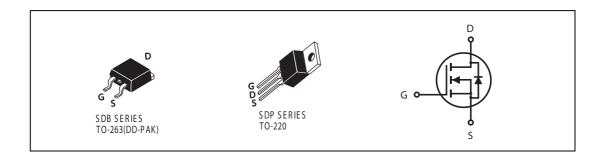
September, 2002

#### N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY				
VDSS	ld	RDS(on) ( m $\Omega$ ) TYP		
30V 55A	12.5 @ VGS = 10V			
	55A	20 @ VGS = 4.5V		

#### **FEATURES**

- Super high dense cell design for extremely low RDS (ON).
- High power and current handling capability.
- TO-220 & TO-263 package.



#### ABSOLUTE MAXIMUM RATINGS (TC=25°C unless otherwise noted)

Parameter	S ymbol	Limit	Unit			
Drain-S ource Voltage	VDS	30	V			
Gate-Source Voltage	VGS	±20	V			
Drain Current-Continuous @ TJ=125℃	lD	55	А			
-Pulsed <sup>a</sup>	IDM	140	А			
Drain-Source Diode Forward Current	Is	55	А			
Maximum Power Dissipation @ Tc=25°C	PD	75	W			
Derate above 25℃		0.5	W/°C			
Operating and Storage Temperature Range	TJ, TSTG	-65 to 175	°C			
THERMAL CHARACTERISTICS						
Thermal Resistance, Junction-to-Case	R øJC	2.5	°C/W			
Thermal Resistance, Junction-to-Ambient	R <i>ө</i> ја	62.5	°C/W			

#### ELECTRICAL CHARACTERISTICS (Tc=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BVDSS	VGS = 0V, ID = 250uA	30			٧		
Zero Gate Voltage Drain Current	loss	VDS = 24V, VGS = 0V			10	uA		
Gate-Body Leakage	lgss	$VGS = \pm 16V, VDS = 0V$			±100	nA		
ON CHARACTERISTICS <sup>a</sup>								
Gate Threshold Voltage	VGS(th)	V DS = V GS , ID = 250uA	1	1.5	3	V		
Drain-Source On-State Resistance	R ds (on)	Vgs = 10V, ld = 27A		12.5	14	m ohm		
		VGS = 4.5V, ID = 22A		20	23	m ohm		
On-State Drain Current	Id(on)	VGS = 10V, VDS = 10V	60			А		
Forward Transconductance	g <sub>FS</sub>	VDS = 10V, ID = 27A		32		S		
DYNAMIC CHARACTERISTICS b								
Input Capacitance	Ciss			930		РF		
Output Capacitance	Coss	V DS =15V, V GS = 0V f =1.0MHz		340		рF		
Reverse Transfer Capacitance	CRSS			120		рF		
SWITCHING CHARACTERISTICS	)							
Turn-On Delay Time	tD(ON)	VDD = 15V,		17	16	ns		
Rise Time	tr	ID = 1A, VGS = 10V, RGEN =60 ohm		23	250	ns		
Turn-Off Delay Time	tD(OFF)			37	90	ns		
Fall Time	tf			20	200	ns		
Total Gate Charge	Qg	VDS=15V, ID=27.5A, VGS=10V		26.1	35	nC		
Total Gate Charge		V <sub>DS</sub> =15V, I <sub>D</sub> =27.5A,V <sub>GS</sub> =4.5V		13.7	16.5	nC		
Gate-Source Charge	Qgs	VDS =15V, ID = 27.5A, VGS =10V		5.4		nC		
Gate-Drain Charge	Qgd			4.6		nC		

#### ELECTRICAL CHARACTERISTICS (Tc=25°C unless otherwise noted)

Parameter	S ymbol	Condition	Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS <sup>a</sup>							
Diode Forward Voltage	VsD	Vgs = 0V, Is =26A		0.9	1.3	V	

#### Notes

a.Pulse Test:Pulse Width  $\leq$  300us, Duty Cycle  $\leq$  2%.

b.Guaranteed by design, not subject to production testing.

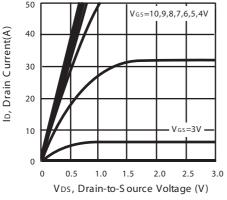


Figure 1. Output Characteristics

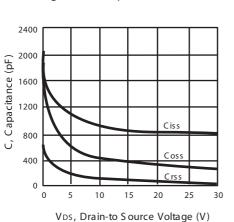


Figure 3. Capacitance

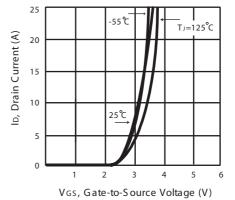


Figure 2. Transfer Characteristics

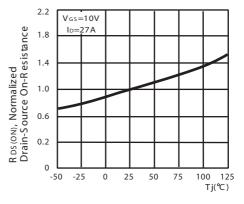
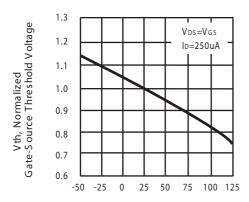
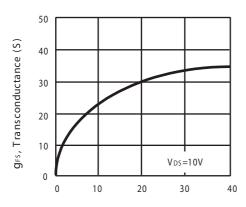


Figure 4. On-Resistance Variation with Temperature



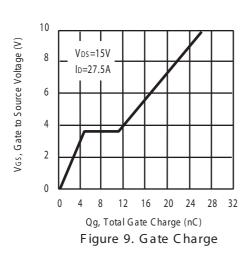
Tj, Junction Temperature (°C)

Figure 5. Gate Threshold Variation with Temperature

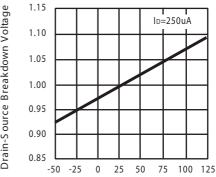


IDS, Drain-Source Current (A)

Figure 7. Transconductance Variation with Drain Current



Drain-Source Breakdown Voltage BVDSS, Normalized



Tj, Junction Temperature (°C)

Figure 6. Breakdown Voltage Variation with Temperature

50 Is, Source-drain current (A) 10 0.1 0.6 0.8 0.4 1.0 1.2

Vsp, Body Diode Forward Voltage (V)

1.4

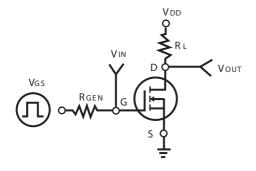
Figure 8. Body Diode Forward Voltage Variation with Source Current

100 D, Drain Current (A) 10

300 200 Vgs=10V Single Pulse 0.1 30 60

VDS, Drain-Source Voltage (V)

Figure 10. Maximum Safe Operating Area



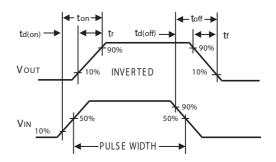


Figure 11. Switching Test Circuit

Figure 12. Switching Waveforms

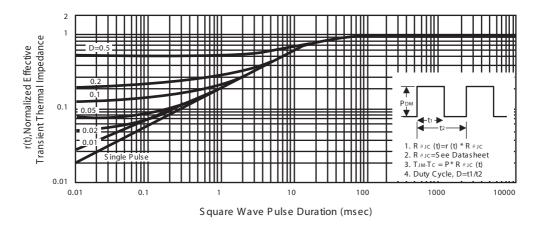


Figure 13. Normalized Thermal Transient Impedance Curve